A	pplication No.	Applicant(s)	
	0/722,193	LEE ET AL.	
Notice of Allowability	xaminer	Art Unit	
В	rook Kebede	2823	
The MAILING DATE of this communication appear. All claims being allowable, PROSECUTION ON THE MERITS IS (O herewith (or previously mailed), a Notice of Allowance (PTOL-85) or NOTICE OF ALLOWABILITY IS NOT A GRANT OF PATENT RIGH of the Office or upon petition by the applicant. See 37 CFR 1.313 are	R REMAINS) CLOSED in this a other appropriate communicati ITS. This application is subjec	application. If not included on will be mailed in due course. THIS	
1. X This communication is responsive to the amendment filed on	February 15, 2006.		
2. ☑ The allowed claim(s) is/are <u>14-16 and 18-27</u> .			
3.	een received. een received in Application No. ments have been received in the this communication to file a rep IT of this application. d. Note the attached EXAMINE reason(s) why the oath or declar e submitted. 's Patent Drawing Review (PTo mendment / Comment or in the feader according to 37 CFR 1.12 of BIOLOGICAL MATERIAL	is national stage application from the ly complying with the requirements ER'S AMENDMENT or NOTICE OF tration is deficient. O-948) attached Office action of wings in the front (not the back) of 1(d). must be submitted. Note the	
Attachment(s) 1. Notice of References Cited (PTO-892) 2. Notice of Draftperson's Patent Drawing Review (PTO-948) 3. Information Disclosure Statements (PTO-1449 or PTO/SB/08), Paper No./Mail Date	 Interview Summa Paper No./Mail D Examiner's Amen 	Date	

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EXAMINER'S AMENDMENT

1. An examiner's amendment to the record appears below. Should the changes and/or

additions be unacceptable to applicant, an amendment may be filed as provided by 37 CFR

1.312. To ensure consideration of such an amendment, it MUST be submitted no later than the

payment of the issue fee.

Authorization for this examiner's amendment was given in a telephone interview with

Mr. Robert N. Crouse on March 1, 2006.

2. The application has been amended as follows:

In the Claims:

Change claim 14 to -- A method of fabricating an integrated circuit device, comprising: forming

a mask layer exposing a predetermined region of a substrate; etching the predetermined

region through the mask layer to form at least one shallow trench in the substrate; forming

a passivation laver comprising epitaxial silicon-germanium in the shallow trench; removing

the mask layer; forming a channel silicon layer on the substrate and on the passivation layer;

patterning the channel silicon layer and the substrate to expose sides of the passivation layer and

to form a trench defining an active region; selectively removing the exposed passivation layer to

form a vacant space; forming a buried insulation layer in the vacant space and forming a field

isolation layer in the trench.--.

Change claim 25 to -- A method of fabricating an integrated circuit device, comprising: forming

at least one passivation layer comprising epitaxially grown silicon-germanium in a

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exposing the predetermined region in the substrate; etching the exposed region through the mask layer to form at least one shallow trench in the substrate; forming the passivation layer in the shallow trench; removing the mask layer; forming a channel silicon layer on the substrate and on the passivation layer; patterning the channel silicon layer and the substrate to expose sides of the passivation layer and to form a trench defining an active region; selectively removing the exposed passivation layer to form a vacant space; forming a buried insulation layer in the vacant space and forming a field isolation layer in the trench; forming a groove exposing top sides of the active region at a boundary between the field isolation layer and the active region; forming a gate electrode on the active region and the field isolation layer so that the gate electrode fills the groove; forming impurity diffusion layers in the active regions on both sides of the gate electrode to provide a source and a drain region, wherein at least one of the source and drain regions is on the buried insulation layer.--.

Allowable Subject Matter

3. Claims 14-16 and 18-27 are allowed over prior art of record.

Reasons for Allowance

4. The following is an examiner's statement of reasons for allowance:

The prior art of record neither anticipates nor renders obvious the claimed subject matter of the instant application as a whole either taken alone or in combination, in particular, prior art of record does not teach "forming a passivation laver comprising epitaxial silicon-germanium in the shallow trench; removing the mask layer; forming a channel silicon layer on the substrate and on the passivation layer; patterning the channel silicon layer and the substrate to expose sides of

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the passivation layer and to form a trench defining an active region; selectively removing the exposed passivation layer to form a vacant space; forming a buried insulation layer in the vacant space and forming a field isolation layer in the trench," as recited in claim 14 and "forming the passivation layer in the shallow trench; removing the mask layer; forming a channel silicon layer on the substrate and on the passivation layer; patterning the channel silicon layer and the substrate to expose sides of the passivation layer and to form a trench defining an active region; selectively removing the exposed passivation layer to form a vacant space; forming a buried insulation layer in the vacant space and forming a field isolation layer in the trench; forming a groove exposing top sides of the active region at a boundary between the field isolation layer and the active region; forming a gate electrode on the active region and the field isolation layer so that the gate electrode fills the groove," as recited in claim 25 respectively.

Claims 15, 16, 18-24, 26 and 27 are also allowed as being directly or indirectly dependent of the allowed independent bas claim.

Conclusion

5. Any comments considered necessary by applicant must be submitted no later than the payment of the issue fee and, to avoid processing delays, should preferably accompany the issue fee. Such submissions should be clearly labeled "Comments on Statement of Reasons for Allowance."

Correspondence

6. Any inquiry concerning this communication or earlier communications from the examiner should be directed to Brook Kebede whose telephone number is (571) 272-1862. The examiner can normally be reached on 8-5 Monday to Friday.

If attempts to reach the examiner by telephone are unsuccessful, the examiner's supervisor, Matthew S. Smith can be reached on (571) 272-1907. The fax phone number for the organization where this application or proceeding is assigned is 571-273-8300.

Information regarding the status of an application may be obtained from the Patent Application Information Retrieval (PAIR) system. Status information for published applications may be obtained from either Private PAIR or Public PAIR. Status information for unpublished applications is available through Private PAIR only. For more information about the PAIR system, see http://pair-direct.uspto.gov. Should you have questions on access to the Private PAIR system, contact the Electronic Business Center (EBC) at 866-217-9197 (toll-free).

Brook Kebede Primary Examiner

Brook Kekede

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BK March 4, 2006